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### Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

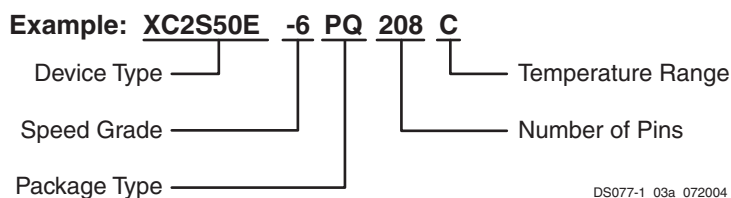
Product Status	Obsolete
Number of LABs/CLBs	1176
Number of Logic Elements/Cells	5292
Total RAM Bits	57344
Number of I/O	146
Number of Gates	200000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/xilinx/xc2s200e-6pqg208c">https://www.e-xfl.com/product-detail/xilinx/xc2s200e-6pqg208c</a>



## Ordering Information

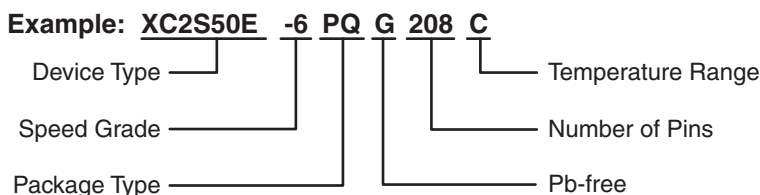
Spartan-IIE devices are available in both standard and Pb-free packaging options for all device/package combinations. The Pb-free packages include a special "G" character in the ordering code.

### Standard Packaging



DS077-1\_03a\_072004

### Pb-Free Packaging



DS077-1\_03b\_072004

## Device Ordering Options

Device	Speed Grade		Package Type / Number of Pins		Temperature Range (T <sub>J</sub> ) <sup>(2)</sup>	
XC2S50E	-6	Standard Performance	TQ(G)144	144-pin Plastic Thin QFP	C = Commercial	0°C to +85°C
XC2S100E	-7	Higher Performance <sup>(1)</sup>	PQ(G)208	208-pin Plastic QFP	I = Industrial	-40°C to +100°C
XC2S150E			FT(G)256	256-ball Fine Pitch BGA		
XC2S200E			FG(G)456	456-ball Fine Pitch BGA		
XC2S300E			FG(G)676	676-ball Fine Pitch BGA		
XC2S400E						
XC2S600E						

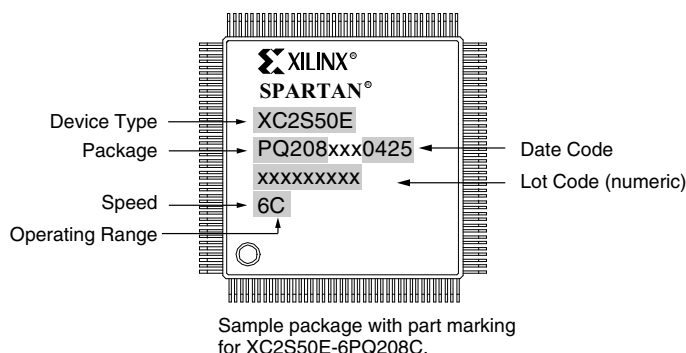
#### Notes:

- The -7 speed grade is exclusively available in the Commercial temperature range.
- See [www.xilinx.com](http://www.xilinx.com) for information on automotive temperature range devices.

## Device Part Marking

Figure 2 is a top marking example for Spartan-IIE FPGAs in the quad-flat packages. The markings for BGA packages are nearly identical to those for the quad-flat packages, except that the marking is rotated with respect to the ball A1 indicator.

The "7C" and "6I" Speed Grade/Temperature Range part combinations may be dual marked as "7C/6I". Devices with the dual mark can be used as either -7C or -6I devices. Devices with a single mark are only guaranteed for the marked speed grade and temperature range.



ds077-1\_02\_072804

**Figure 2: Spartan-IIE QFP Marking Example**

Table 7 shows the depth and width aspect ratios for the block RAM.

Table 7: Block RAM Port Aspect Ratios

Width	Depth	ADDR Bus	Data Bus
1	4096	ADDR<11:0>	DATA<0>
2	2048	ADDR<10:0>	DATA<1:0>
4	1024	ADDR<9:0>	DATA<3:0>
8	512	ADDR<8:0>	DATA<7:0>
16	256	ADDR<7:0>	DATA<15:0>

The Spartan-IIE FPGA block RAM also includes dedicated routing to provide an efficient interface with both CLBs and other block RAMs. See Xilinx Application Note [XAPP173](#) for more information on block RAM.

## Programmable Routing

It is the longest delay path that limits the speed of any design. Consequently, the Spartan-IIE FPGA routing architecture and its place-and-route software were defined jointly to minimize long-path delays and yield the best system performance.

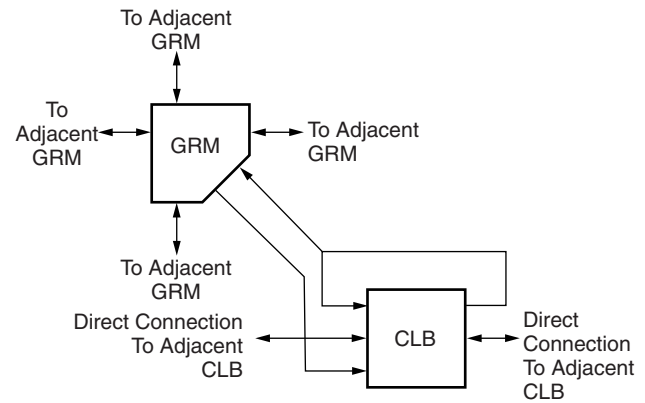
The joint optimization also reduces design compilation times because the architecture is software-friendly. Design cycles are correspondingly reduced due to shorter design iteration times.

The software automatically uses the best available routing based on user timing requirements. The details are provided here for reference.

### Local Routing

The local routing resources, as shown in Figure 9, provide the following three types of connections:

- Interconnections among the LUTs, flip-flops, and General Routing Matrix (GRM), described below.
- Internal CLB feedback paths that provide high-speed connections to LUTs within the same CLB, chaining them together with minimal routing delay
- Direct paths that provide high-speed connections between horizontally adjacent CLBs, eliminating the delay of the GRM



DS001\_06\_032300

Figure 9: Spartan-IIE Local Routing

### General Purpose Routing

Most Spartan-IIE FPGA signals are routed on the general purpose routing, and consequently, the majority of interconnect resources are associated with this level of the routing hierarchy. The general routing resources are located in horizontal and vertical routing channels associated with the rows and columns of CLBs. The general-purpose routing resources are listed below.

- Adjacent to each CLB is a General Routing Matrix (GRM). The GRM is the switch matrix through which horizontal and vertical routing resources connect, and is also the means by which the CLB gains access to the general purpose routing.
- 24 single-length lines route GRM signals to adjacent GRMs in each of the four directions.
- 96 buffered Hex lines route GRM signals to other GRMs six blocks away in each one of the four directions. Organized in a staggered pattern, Hex lines may be driven only at their endpoints. Hex-line signals can be accessed either at the endpoints or at the midpoint (three blocks from the source). One third of the Hex lines are bidirectional, while the remaining ones are unidirectional.
- 12 Longlines are buffered, bidirectional wires that distribute signals across the device quickly and efficiently. Vertical Longlines span the full height of the device, and horizontal ones span the full width of the device.

### I/O Routing

Spartan-IIE devices have additional routing resources around their periphery that form an interface between the CLB array and the IOBs. This additional routing, called the VersaRing™ routing, facilitates pin-swapping and pin-locking, such that logic redesigns can adapt to existing PCB layouts. Time-to-market is reduced, since PCBs and other system components can be manufactured while the logic design is still in progress.

Table 11: Configuration Modes

Configuration Mode	Preconfiguration Pull-ups	M0	M1	M2	CCLK Direction	Data Width	Serial D <sub>OUT</sub>
Master Serial mode	No	0	0	0	Out	1	Yes
	Yes	0	0	1			
Slave Parallel mode (SelectMAP)	Yes	0	1	0	In	8	No
	No	0	1	1			
Boundary-Scan mode	Yes	1	0	0	N/A	1	No
	No	1	0	1			
Slave Serial mode	Yes	1	1	0	In	1	Yes
	No	1	1	1			

**Notes:**

1. During power-on and throughout configuration, the I/O drivers will be in a high-impedance state. After configuration, all unused I/Os (those not assigned signals) will remain in a high-impedance state. Pins used as outputs may pulse High at the end of configuration (see [Answer 10504](#)).
2. If the Mode pins are set for preconfiguration pull-ups, those resistors go into effect once the rising edge of INIT samples the Mode pins. They will stay in effect until GTS is released during startup, after which the UnusedPin bitstream generator option will determine whether the unused I/Os have a pull-up, pull-down, or no resistor.

## Signals

There are two kinds of pins that are used to configure Spartan-IIE devices: Dedicated pins perform only specific configuration-related functions; the other pins can serve as general purpose I/Os once user operation has begun.

The dedicated pins comprise the mode pins (M2, M1, M0), the configuration clock pin (CCLK), the **PROGRAM** pin, the **DONE** pin and the boundary-scan pins (TDI, TDO, TMS, TCK). Depending on the selected configuration mode, CCLK may be an output generated by the FPGA, or may be generated externally, and provided to the FPGA as an input.

Note that some configuration pins can act as outputs. For correct operation, these pins require a  $V_{CCO}$  of 3.3V to drive an LVTTTL signal or 2.5V to drive an LVCMOS signal. All the relevant pins fall in banks 2 or 3. The **CS** and **WRITE** pins for Slave Parallel mode are located in bank 1.

For a more detailed description than that given below, see [Module 1](#) and [XAPP176](#), *Configuration and Readback of the Spartan-II and Spartan-IIE FPGA Families*.

## The Process

The sequence of steps necessary to configure Spartan-IIE devices are shown in [Figure 16](#). The overall flow can be divided into three different phases.

- Initiating configuration
- Configuration memory clear

- Loading data frames
- Start-up

The memory clearing and start-up phases are the same for all configuration modes; however, the steps for the loading of data frames are different. Thus, the details for data frame loading are described separately in the sections devoted to each mode.

### Initiating Configuration

There are two different ways to initiate the configuration process: applying power to the device or asserting the **PROGRAM** input.

Configuration on power-up occurs automatically unless it is delayed by the user, as described in a separate section below. The waveform for configuration on power-up is shown in [Configuration Switching Characteristics, page 48](#). Before configuration can begin,  $V_{CCO}$  Bank 2 must be greater than 1.0V. Furthermore, all  $V_{CCINT}$  power pins must be connected to a 1.8V supply. For more information on delaying configuration, see [Clearing Configuration Memory, page 23](#).

Once in user operation, the device can be re-configured simply by pulling the **PROGRAM** pin Low. The device acknowledges the beginning of the configuration process by driving **DONE** Low, then enters the memory-clearing phase.

During start-up, the device performs four operations:

1. The assertion of DONE. The failure of DONE to go High may indicate the unsuccessful loading of configuration data.
2. The release of the Global Three State (GTS). This activates all the I/Os to which signals are assigned. The remaining I/Os stay in a high-impedance state with internal weak pull-up resistors present.
3. The release of the Global Set Reset (GSR). This allows all flip-flops to change state.
4. The assertion of Global Write Enable (GWE). This allows all RAMs and flip-flops to change state.

By default, these operations are synchronized to CCLK. The entire start-up sequence lasts eight cycles, called C0-C7, after which the loaded design is fully functional. The four operations can be selected to switch on any CCLK cycle C1-C6 through settings in the Xilinx Development Software. The default timing for start-up is shown in the top half of Figure 17; heavy lines show default settings.

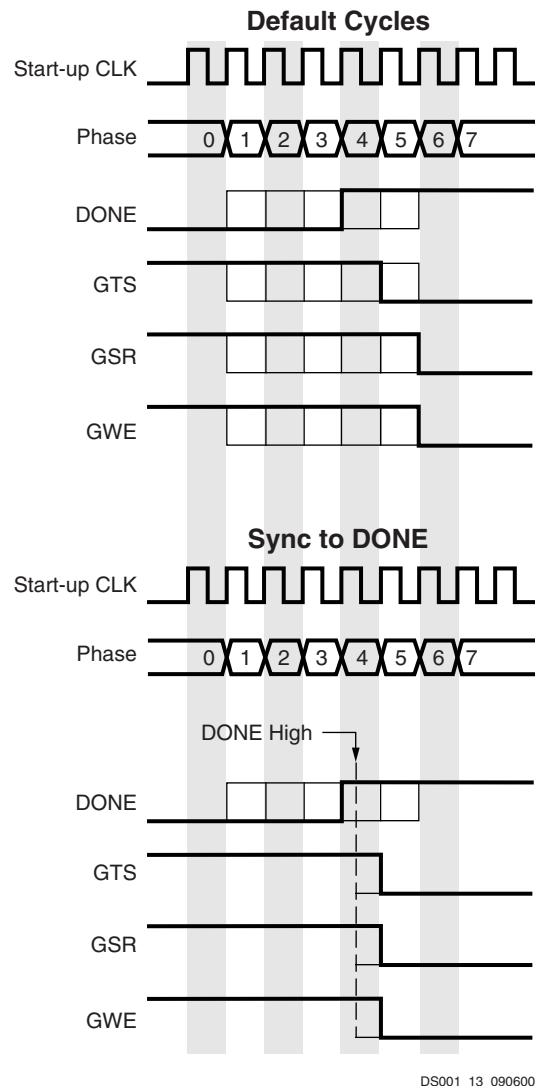
The default Start-up sequence is that one CCLK cycle after DONE goes High, the global 3-state signal (GTS) is released. This permits device outputs to turn on as necessary.

One CCLK cycle later, the Global Set/Reset (GSR) and Global Write Enable (GWE) signals are released. This permits the internal storage elements to begin changing state in response to the logic and the user clock.

The bottom half of Figure 17 shows another commonly used version of the start-up timing known as Sync-to-DONE. This version makes the GTS, GSR, and GWE events conditional upon the DONE pin going High. This timing is important for a daisy chain of multiple FPGAs in serial mode, since it ensures that all FPGAs go through start-up together, after all their DONE pins have gone High.

Sync-to-DONE timing is selected by setting the GTS, GSR, and GWE cycles to a value of DONE in the configuration options. This causes these signals to transition one clock cycle after DONE externally transitions High.

The sequence can also be paused at any stage until lock has been achieved on any or all DLLs.



DS001\_13\_090600

Figure 17: Start-Up Waveforms

## Serial Modes

There are two serial configuration modes. In Master Serial mode, the FPGA controls the configuration process by driving CCLK as an output. In Slave Serial mode, the FPGA passively receives CCLK as an input from an external agent (e.g., a microprocessor, CPLD, or second FPGA in master mode) that is controlling the configuration process. In both modes, the FPGA is configured by loading one bit per CCLK cycle. The MSB of each configuration data byte is always written to the DIN pin first.

See Figure 18 for the sequence for loading data into the Spartan-IIIE FPGA serially. This is an expansion of the "Load Configuration Data Frames" block in Figure 16, page 23. Note that  $\overline{CS}$  and  $\overline{WRITE}$  are not normally used during serial configuration. To ensure successful loading of the FPGA, do not toggle  $\overline{WRITE}$  with  $\overline{CS}$  Low during serial configuration.

## Revision History

Date	Version	Description
11/15/2001	1.0	Initial Xilinx release.
11/18/2002	2.0	Added XC2S400E and XC2S600E. Removed Preliminary designation. Clarified details of I/O standards, boundary scan, and configuration.
07/09/2003	2.1	Added hot swap description (see <a href="#">Hot Swap</a> , <a href="#">Hot Insertion</a> , <a href="#">Hot Socketing Support</a> ). Added <a href="#">Table 9</a> containing JTAG IDCODE values. Clarified configuration PROM support.
06/18/2008	2.3	Added note that TDI, TMS, and TCK have a default pull-up resistor. Add note on maximum daisy-chain limit. Updated <a href="#">Figure 19</a> since Mode pins can be pulled up to either 2.5V or 3.3V. Updated all modules for continuous page, figure, and table numbering. Updated links. Synchronized all modules to v2.3.
08/09/2013	3.0	This product is obsolete/discontinued per <a href="#">XCN12026</a> .

### Global Clock Setup and Hold for LVTTL Standard, *with* DLL (Pin-to-Pin)

Symbol	Description	Speed Grade		Units
		-7	-6	
		Min	Min	
$T_{PSDLL} / T_{PHDLL}$	Input setup and hold time relative to global clock input signal for LVTTL standard, no delay, IFF, <sup>(1)</sup> <i>with</i> DLL	1.6 / 0	1.7 / 0	ns

**Notes:**

1. IFF = Input Flip-Flop or Latch
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. DLL output jitter is already included in the timing calculation.
4. For data input with different standards, adjust the setup time delay by the values shown in [IOB Input Delay Adjustments for Different Standards, page 38](#). For a global clock input with standards other than LVTTL, adjust delays with values from the [I/O Standard Global Clock Input Adjustments, page 42](#).
5. A zero hold time listing indicates no hold time or a negative hold time.

### Global Clock Setup and Hold for LVTTL Standard, *without* DLL (Pin-to-Pin)

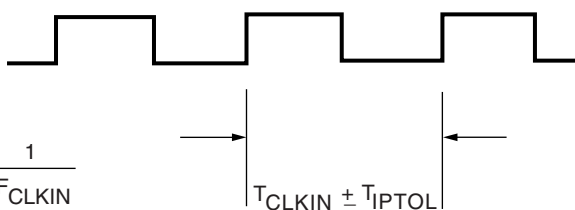
Symbol	Description	Device	Speed Grade		Units
			-7	-6	
			Min	Min	
$T_{PSFD} / T_{PHFD}$	Input setup and hold time relative to global clock input signal for LVTTL standard, with delay, IFF, <sup>(1)</sup> <i>without</i> DLL	XC2S50E	1.8 / 0	1.8 / 0	ns
		XC2S100E	1.8 / 0	1.8 / 0	ns
		XC2S150E	1.9 / 0	1.9 / 0	ns
		XC2S200E	1.9 / 0	1.9 / 0	ns
		XC2S300E	2.0 / 0	2.0 / 0	ns
		XC2S400E	2.0 / 0	2.0 / 0	ns
		XC2S600E	2.1 / 0	2.1 / 0	ns

**Notes:**

1. IFF = Input Flip-Flop or Latch
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. For data input with different standards, adjust the setup time delay by the values shown in [IOB Input Delay Adjustments for Different Standards, page 38](#). For a global clock input with standards other than LVTTL, adjust delays with values from the [I/O Standard Global Clock Input Adjustments, page 42](#).

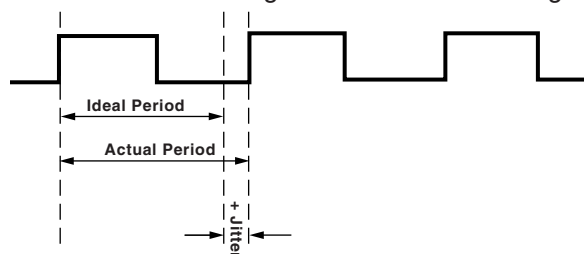


**Period Tolerance:** the allowed input clock period change in nanoseconds.

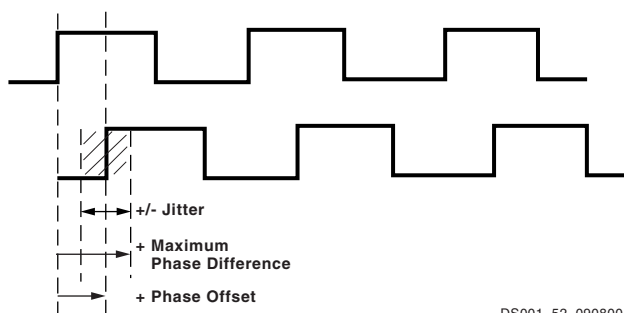
$$T_{CLKIN} = \frac{1}{F_{CLKIN}}$$


$T_{CLKIN} \pm T_{IPTOL}$

**Output Jitter:** the difference between an ideal reference clock edge and the actual design.



**Phase Offset and Maximum Phase Difference**



DS001\_52\_090800

**Figure 22: Period Tolerance and Clock Jitter**

## CLB Distributed RAM Switching Characteristics

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Sequential Delays						
T <sub>SHCKO16</sub>	Clock CLK to X/Y outputs (WE active, 16 x 1 mode)	0.6	1.5	0.6	1.7	ns
T <sub>SHCKO32</sub>	Clock CLK to X/Y outputs (WE active, 32 x 1 mode)	0.8	1.9	0.8	2.1	ns
Setup/Hold Times with Respect to Clock CLK						
T <sub>AS</sub> / T <sub>AH</sub>	F/G address inputs	0.42 / 0	-	0.5 / 0	-	ns
T <sub>DS</sub> / T <sub>DH</sub>	BX/BY data inputs (DIN)	0.53 / 0	-	0.6 / 0	-	ns
T <sub>WS</sub> / T <sub>WH</sub>	CE input (WS)	0.7 / 0	-	0.8 / 0	-	ns
Clock CLK						
T <sub>WPH</sub>	Pulse width, High	2.1	-	2.4	-	ns
T <sub>WPL</sub>	Pulse width, Low	2.1	-	2.4	-	ns
T <sub>WC</sub>	Clock period to meet address write cycle time	4.2	-	4.8	-	ns

## CLB Shift Register Switching Characteristics

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Sequential Delays						
T <sub>REG</sub>	Clock CLK to X/Y outputs	1.2	2.9	1.2	3.2	ns
Setup/Hold Times with Respect to Clock CLK						
T <sub>SHDICK</sub>	BX/BY data inputs (DIN)	0.53 / 0	-	0.6 / 0	-	ns
T <sub>SHCECK</sub>	CE input (WS)	0.7 / 0	-	0.8 / 0	-	ns
Clock CLK						
T <sub>SRPH</sub>	Pulse width, High	2.1	-	2.4	-	ns
T <sub>SRPL</sub>	Pulse width, Low	2.1	-	2.4	-	ns

## Block RAM Switching Characteristics

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Sequential Delays						
T <sub>BCKO</sub>	Clock CLK to DOUT output	0.6	3.1	0.6	3.5	ns
Setup/Hold Times with Respect to Clock CLK						
T <sub>BACK</sub> / T <sub>BCKA</sub>	ADDR inputs	1.0 / 0	-	1.1 / 0	-	ns
T <sub>BDCK</sub> / T <sub>BCKD</sub>	DIN inputs	1.0 / 0	-	1.1 / 0	-	ns
T <sub>BECK</sub> / T <sub>BCKE</sub>	EN inputs	2.2 / 0	-	2.5 / 0	-	ns
T <sub>BRCK</sub> / T <sub>BCKR</sub>	RST input	2.1 / 0	-	2.3 / 0	-	ns
T <sub>BWCK</sub> / T <sub>BCKW</sub>	WEN input	2.0 / 0	-	2.2 / 0	-	ns
Clock CLK						
T <sub>BPWH</sub>	Pulse width, High	1.4	-	1.5	-	ns
T <sub>BPWL</sub>	Pulse width, Low	1.4	-	1.5	-	ns
T <sub>BCCS</sub>	CLKA -> CLKB setup time for different ports	2.7	-	3.0	-	ns

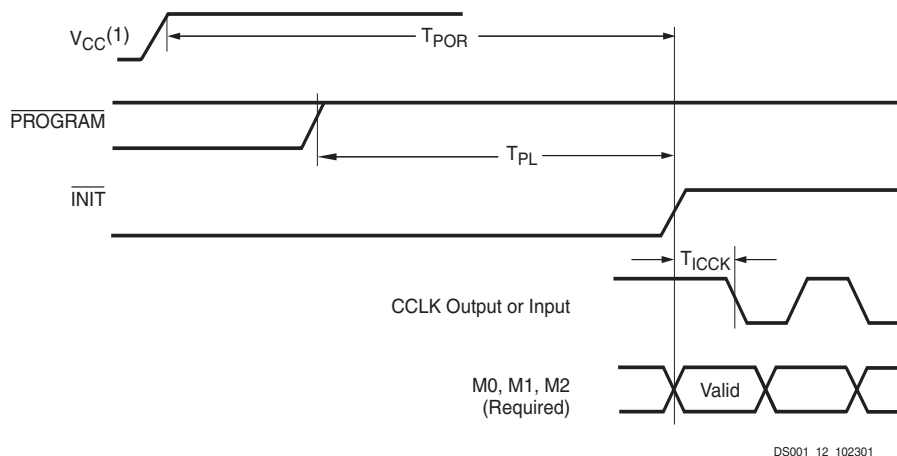
## TBUF Switching Characteristics

Symbol	Description	Speed Grade		Units
		-7	-6	
		Max	Max	
$T_{IO}$	IN input to OUT output	0	0	ns
$T_{OFF}$	TRI input to OUT output high impedance	0.1	0.11	ns
$T_{ON}$	TRI input to valid data on OUT output	0.1	0.11	ns

## JTAG Test Access Port Switching Characteristics

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Setup/Hold Times with Respect to TCK						
T <sub>TAPTCK</sub> / T <sub>TCKTAP</sub>	TMS and TDI setup times and hold times	4.0 / 2.0	-	4.0 / 2.0	-	ns
Sequential Delays						
T <sub>TCKTDO</sub>	Output delay from clock TCK to output TDO	-	11.0	-	11.0	ns
F <sub>TCK</sub>	TCK clock frequency	-	33	-	33	MHz

## Configuration Switching Characteristics



DS001\_12\_102301

Symbol	Description	All Devices		Units
		Min	Max	
$T_{POR}$	Power-on reset	-	2	ms
$T_{PL}$	Program latency	-	100	μs
$T_{ICCK}$	CCLK output delay (Master serial mode only)	0.5	4	μs
$T_{PROGRAM}$	Program pulse width	300	-	ns

### Notes:

- Before configuration can begin,  $V_{CCINT}$  and  $V_{CCO}$  Bank 2 must reach the recommended operating voltage.

**Figure 23: Configuration Timing on Power-Up**



## Spartan-IIE FPGA Family: Pinout Tables

DS077-4 (v3.0) August 9, 2013

Product Specification

### Introduction

This section describes how the various pins on a Spartan®-IIE FPGA connect within the supported component packages, and provides device-specific thermal characteristics. Spartan-IIE FPGAs are available in both standard and Pb-free, RoHS versions of each package, with the Pb-free version adding a “G” to the middle of the package code. Except for the thermal characteristics, all information for the standard package applies equally to the Pb-free package.

### Pin Types

Most pins on a Spartan-IIE FPGA are general-purpose, user-defined I/O pins. There are, however, different functional types of pins on Spartan-IIE FPGA packages, as outlined below.

### Pin Definitions

Pad Name	Dedicated Pin	Direction	Description
GCK0, GCK1, GCK2, GCK3	No	Input	Clock input pins that connect to Global Clock buffers or DLL inputs. These pins become user inputs when not needed for clocks.
DLL	No	Input	Clock input pins that connect to DLL input or feedback clocks. Differential clock input (N input of pair) when paired with adjacent GCK input. Becomes a user I/O when not needed for clocks.
M0, M1, M2	Yes	Input	Mode pins used to specify the configuration mode.
CCLK	Yes	Input or Output	The configuration Clock I/O pin. It is an input for Slave Parallel and Slave Serial modes, and output in Master Serial mode. After configuration, it is an input only with Don't Care logic levels.
PROGRAM	Yes	Input	Initiates a configuration sequence when asserted Low.
DONE	Yes	Bidirectional	Indicates that configuration loading is complete, and that the start-up sequence is in progress. The output may be open drain.
INIT	No	Bidirectional (Open-drain)	When Low, indicates that the configuration memory is being cleared. Goes High to indicate the end of initialization. Goes back Low to indicate a CRC error. This pin becomes a user I/O after configuration.
DOUT/BUSY	No	Output	In Slave Parallel mode, BUSY controls the rate at which configuration data can be loaded. It is not needed below 50 MHz. This pin becomes a user I/O after configuration unless the Slave Parallel port is retained.  In serial modes, DOUT provides configuration data to downstream devices in a daisy-chain. This pin becomes a user I/O after configuration.

**PQ208 Pinouts (XC2S50E, XC2S100E, XC2S150E, XC2S200E, XC2S300E)**

Pad Name		Pin	LVDS Async. Output Option	V <sub>REF</sub> Option
Function	Bank			
I/O	2	P134	-	-
I/O (D3), L17N	2	P135	XC2S50E, 300E	-
I/O, VREF Bank 2, L17P	2	P136	XC2S50E, 300E	All
GND	-	P137	-	-
I/O, L16N_YY	2	P138	All	-
I/O, L16P_YY	2	P139	All	-
I/O, L15N_YY	2	P140	All	-
I/O (D2), L15P_YY	2	P141	All	-
VCCINT	-	P142	-	-
VCCO	-	P143	-	-
GND	-	P144	-	-
I/O (D1), L14N	2	P145	XC2S50E, 300E	-
I/O, L14P	2	P146	XC2S50E, 300E	XC2S100E, 150E, 200E, 300E
I/O	2	P147	-	-
I/O	2	P148	-	-
I/O	2	P149	-	-
I/O, VREF Bank 2, L13N	2	P150	XC2S100E, 150E	All
I/O, L13P	2	P151	XC2S100E, 150E	-
I/O	2	P152	-	XC2S200E, 300E
I/O (DIN, D0), L12N_YY	2	P153	All	-
I/O (DOUT, BUSY), L12P_YY	2	P154	All	-
CCLK	2	P155	-	-

**PQ208 Pinouts (XC2S50E, XC2S100E, XC2S150E, XC2S200E, XC2S300E)**

Pad Name		Pin	LVDS Async. Output Option	V <sub>REF</sub> Option
Function	Bank			
VCCO	-	P156	-	-
TDO	2	P157	-	-
GND	-	P158	-	-
TDI	-	P159	-	-
I/O ( $\overline{CS}$ ), L11P_YY	1	P160	All	-
I/O ( $\overline{WRITE}$ ), L11N_YY	1	P161	All	-
I/O	1	P162	-	XC2S200E, 300E
I/O	1	P163	-	-
I/O, VREF Bank 1, L10P_YY	1	P164	All	All
I/O, L10N_YY	1	P165	All	-
I/O	1	P166	-	-
I/O	1	P167	-	-
I/O, L9P	1	P168	XC2S50E, 100E, 200E, 300E	XC2S100E, 150E, 200E, 300E
I/O, L9N	1	P169	XC2S50E, 100E, 200E, 300E	-
GND	-	P170	-	-
VCCO	-	P171	-	-
VCCINT	-	P172	-	-
I/O, L8P	1	P173	XC2S50E, 100E, 200E, 300E	-
I/O, L8N	1	P174	XC2S50E, 100E, 200E, 300E	-
I/O, L7P	1	P175	XC2S50E, 200E, 300E	-
I/O, L7N	1	P176	XC2S50E, 200E, 300E	-
GND	-	P177	-	-

**FT256 Pinouts (XC2S50E, XC2S100E,  
XC2S150E, XC2S200E, XC2S300E, XC2S400E)  
(Continued)**

Pad Name		Pin	LVDS Async. Output Option	V <sub>REF</sub> Option
Function	Bank			
I/O, L51P	4	N9	XC2S50E, 150E, 200E, 400E	-
I/O, L50N	4	T10	XC2S50E, 200E, 300E, 400E	-
I/O, VREF Bank 4, L50P	4	R10	XC2S50E, 200E, 300E, 400E	All
I/O, L49N	4	P10	XC2S50E, 200E, 300E, 400E	-
I/O, L49P	4	R11	XC2S50E, 200E, 300E, 400E	-
I/O	4	T11	-	-
I/O, L48N	4	N10	XC2S50E, 100E, 200E, 300E, 400E	-
I/O, L48P	4	M10	XC2S50E, 100E, 200E, 300E, 400E	-
I/O, L47N	4	P11	XC2S50E, 100E, 200E, 300E, 400E	-
I/O, L47P	4	R12	XC2S50E, 100E, 200E, 300E, 400E	XC2S100E, 150E, 200E, 300E, 400E
I/O, L46N	4	T12	XC2S50E, 100E, 150E, 300E	-
I/O, L46P	4	T13	XC2S50E, 100E, 150E, 300E	-
I/O, L45N_YY	4	N11	All	-
I/O, VREF Bank 4, L45P_YY	4	M11	All	All
I/O, L44N_YY	4	P12	All	-
I/O, L44P_YY	4	N12	All	-

**FT256 Pinouts (XC2S50E, XC2S100E,  
XC2S150E, XC2S200E, XC2S300E, XC2S400E)  
(Continued)**

Pad Name		Pin	LVDS Async. Output Option	V <sub>REF</sub> Option
Function	Bank			
I/O, L43N	4	R13	XC2S50E, 150E	XC2S200E, 300E, 400E
I/O, L43P	4	P13	XC2S50E, 150E	-
I/O, L42N_YY	4	T14	All	-
I/O, L42P_YY	4	R14	All	-
DONE	3	T15	-	-
PROGRAM	-	R16	-	-
I/O ( $\overline{\text{INIT}}$ ), L41N_YY	3	P15	All	-
I/O (D7), L41P_YY	3	P16	All	-
I/O, L40N	3	N15	XC2S100E, 150E, 400E	-
I/O, L40P	3	N16	XC2S100E, 150E, 400E	XC2S200E, 300E, 400E
I/O, L39N	3	N14	XC2S50E, 100E, 150E, 200E, 300E <sup>(1)</sup>	-
I/O, L39P	3	M14	XC2S50E, 100E, 150E, 200E, 300E <sup>(1)</sup>	-
I/O, VREF Bank 3, L38N	3	M15	XC2S50E, 150E, 200E, 300E, 400E	All
I/O, L38P	3	M16	XC2S50E, 150E, 200E, 300E, 400E	-
I/O <sup>(2)</sup>	3	M13	-	-
I/O <sup>(2)</sup>	3	L14	-	-
I/O, L36N	3	L15	XC2S50E, 300E, 400E	XC2S100E, 150E, 200E, 300E, 400E
I/O (D6), L36P	3	L16	XC2S50E, 300E, 400E	-

**Additional FT256 Package Pins (Continued)**

<b>VCCO Bank 5 Pins</b>				
L7	L8	M8	-	-
<b>VCCO Bank 6 Pins</b>				
J5	J6	K6	-	-
<b>VCCO Bank 7 Pins</b>				
G6	H5	H6	-	-
<b>GND Pins</b>				
A1	A16	B2	B15	F6
F11	G7	G8	G9	G10
H7	H8	H9	H10	J7
J8	J9	J10	K7	K8
K9	K10	L6	L11	R2
R15	T1	T16	-	-

**FG456 Pinouts (XC2S100E, XC2S150E, XC2S200E, XC2S300E, XC2S400E, XC2S600E)**

Pad Name		Pin	LVDS Async. Output Option	V <sub>REF</sub> Option	Device-Specific Pinouts: XC2S					
Function	Bank				100E	150E	200E	300E	400E	600E
I/O, L#P_Y	6	R2	XC2S300E, 400E, 600E	-	I/O, L69P	I/O, L92P	I/O, L97P	I/O, L97P_Y	I/O, L97P_Y	I/O, L97P_Y
I/O, VREF Bank 6, L#N_Y	6	R3	XC2S300E, 400E, 600E	All	I/O, VREF Bank 6, L69N	I/O, VREF Bank 6, L92N	I/O, VREF Bank 6, L97N	I/O, VREF Bank 6, L97N_Y	I/O, VREF Bank 6, L97N_Y	I/O, VREF Bank 6, L97N_Y
I/O	6	R4	-	-	-	-	-	I/O	I/O	I/O
I/O	6	R5	-	-	I/O	I/O	I/O	I/O	I/O	I/O
I/O, L#P	6	T2	XC2S200E, 400E, 600E	XC2S600E	I/O, L68P	I/O, L91P	I/O, L96P_Y	I/O, L96P	I/O, L96P_Y	I/O, VREF Bank 6, L96P_Y
I/O, L#N	6	T3	XC2S200E, 400E, 600E	-	I/O, L68N	I/O, L91N	I/O, L96N_Y	I/O, L96N	I/O, L96N_Y	I/O, L96N_Y
I/O, L#P_Y	6	T4	XC2S150E, 300E, 400E	-	-	I/O, L90P_Y	I/O, L95P	I/O, L95P_Y	I/O, L95P_Y	I/O, L95P
I/O, L#N_Y	6	T5	XC2S150E, 300E, 400E	-	-	I/O, L90N_Y	I/O, L95N	I/O, L95N_Y	I/O, L95N_Y	I/O, L95N
I/O, L#P_Y	6	T1	XC2S150E, 200E, 300E, 400E, 600E	-	I/O, L67P	I/O, L89P_Y	I/O, L94P_Y	I/O, L94P_Y	I/O, L94P_Y	I/O, L94P_Y
I/O, VREF Bank 6, L#N_Y	6	U1	XC2S150E, 200E, 300E, 400E, 600E	All	I/O, VREF Bank 6, L67N	I/O, VREF Bank 6, L89N_Y	I/O, VREF Bank 6, L94N_Y	I/O, VREF Bank 6, L94N_Y	I/O, VREF Bank 6, L94N_Y	I/O, VREF Bank 6, L94N_Y
I/O	6	U2	XC2S100E	-	I/O, L66P_Y	I/O	I/O	I/O	I/O	I/O
I/O, L#P_Y	6	U3	XC2S100E, 150E, 200E, 300E, 400E, 600E	-	I/O, L66N_Y	I/O, L88P_Y	I/O, L93P_Y	I/O, L93P_Y	I/O, L93P_Y	I/O, L93P_Y
I/O, L#N_Y	6	U4	XC2S150E, 200E, 300E, 400E, 600E	-	-	I/O, L88N_Y	I/O, L93N_Y	I/O, L93N_Y	I/O, L93N_Y	I/O, L93N_Y
I/O	6	V1	-	-	-	-	-	I/O	I/O	I/O
I/O, L#P_Y	6	W1	XC2S100E, 200E, 300E, 600E	-	I/O, L65P_Y	I/O, L87P	I/O, L92P_Y	I/O, L92P_Y	I/O, L92P	I/O, L92P_Y
I/O, L#N_Y	6	V2	XC2S100E, 200E, 300E, 600E	XC2S200E, 300E, 400E, 600E	I/O, L65N_Y	I/O, L87N	I/O, VREF Bank 6, L92N_Y	I/O, VREF Bank 6, L92N_Y	I/O, VREF Bank 6, L92N	I/O, VREF Bank 6, L92N_Y
I/O	6	W2	-	-	I/O	I/O	I/O	I/O	I/O	I/O
I/O, L#P_Y	6	V3	XC2S200E, 300E, 400E	-	-	I/O, L86P	I/O, L91P_Y	I/O, L91P_Y	I/O, L91P_Y	I/O, L91P
I/O, L#N_Y	6	V4	XC2S200E, 300E, 400E	-	-	I/O, L86N	I/O, L91N_Y	I/O, L91N_Y	I/O, L91N_Y	I/O, L91N
I/O	6	Y1	-	-	-	-	-	I/O	I/O	I/O
I/O, L#P_YY	6	Y2	All	-	I/O, L64P_YY	I/O, L85P_YY	I/O, L90P_YY	I/O, L90P_YY	I/O, L90P_YY	I/O, L90P_YY
I/O, L#N_YY	6	W3	All	-	I/O, L64N_YY	I/O, L85N_YY	I/O, L90N_YY	I/O, L90N_YY	I/O, L90N_YY	I/O, L90N_YY
M1	-	U5	-	-	M1	M1	M1	M1	M1	M1



**FG456 Pinouts (XC2S100E, XC2S150E, XC2S200E, XC2S300E, XC2S400E, XC2S600E)**

Pad Name		Pin	LVDS Async. Output Option	V <sub>REF</sub> Option	Device-Specific Pinouts: XC2S					
Function	Bank				100E	150E	200E	300E	400E	600E
I/O, L#N	4	AA16	XC2S150E, 200E, 400E	XC2S600E	I/O, L46N	I/O, L62N_Y	I/O, L66N_Y	I/O, L66N	I/O, L66N_Y	I/O, VREF Bank 4, L66N
I/O, L#P	4	Y16	XC2S150E, 200E, 400E	-	I/O, L46P	I/O, L62P_Y	I/O, L66P_Y	I/O, L66P	I/O, L66P_Y	I/O, L66P
I/O, L#N	4	W16	XC2S150E, 200E	-	-	I/O, L61N_Y	I/O, L65N_Y	I/O, L65N	I/O, L65N	I/O, L65N
I/O, L#P	4	V16	XC2S150E, 200E	-	-	I/O, L61P_Y	I/O, L65P_Y	I/O, L65P	I/O, L65P	I/O, L65P
I/O, L#N_YY	4	AA17	All	-	I/O, L45N_YY	I/O, L60N_YY	I/O, L64N_YY	I/O, L64N_YY	I/O, L64N_YY	I/O, L64N_YY
I/O, VREF Bank 4, L#P_YY	4	Y17	All	All	I/O, VREF Bank 4, L45P_YY	I/O, VREF Bank 4, L60P_YY	I/O, VREF Bank 4, L64P_YY	I/O, VREF Bank 4, L64P_YY	I/O, VREF Bank 4, L64P_YY	I/O, VREF Bank 4, L64P_YY
I/O	4	AB18	XC2S100E	-	I/O, L44N_Y	I/O	I/O	I/O	I/O	I/O
I/O, L#N	4	W17	XC2S100E, 400E, 600E	-	I/O, L44P_Y	I/O, L59N	I/O, L63N	I/O, L63N	I/O, L63N_Y	I/O, L63N_Y
I/O, L#P	4	V17	XC2S400E, 600E	-	-	I/O, L59P	I/O, L63P	I/O, L63P	I/O, L63P_Y	I/O, L63P_Y
I/O	4	AA18	-	-	-	-	-	I/O	I/O	I/O
I/O, L#N	4	Y18	XC2S100E, 200E, 300E, 400E, 600E	-	I/O, L43N_Y	I/O, L58N	I/O, L62N_Y	I/O, L62N_Y	I/O, L62N_Y	I/O, L62N_Y
I/O, L#P	4	W18	XC2S100E, 200E, 300E, 400E, 600E	XC2S200E, 300E, 400E, 600E	I/O, L43P_Y	I/O, L58P	I/O, VREF Bank 4, L62P_Y	I/O, VREF Bank 4, L62P_Y	I/O, VREF Bank 4, L62P_Y	I/O, VREF Bank 4, L62P_Y
I/O	4	AB19	-	-	I/O	I/O	I/O	I/O	I/O	I/O
I/O, L#N	4	AA19	XC2S150E, 400E	-	-	I/O, L57N_Y	I/O, L61N	I/O, L61N	I/O, L61N_Y	I/O, L61N
I/O, L#P	4	Y19	XC2S150E, 400E	-	-	I/O, L57P_Y	I/O, L61P	I/O, L61P	I/O, L61P_Y	I/O, L61P
I/O	4	AB21	-	-	-	-	-	I/O	I/O	I/O
I/O, L#N_YY	4	AB20	All	-	I/O, L42N_YY	I/O, L56N_YY	I/O, L60N_YY	I/O, L60N_YY	I/O, L60N_YY	I/O, L60N_YY
I/O, L#P_YY	4	AA20	All	-	I/O, L42P_YY	I/O, L56P_YY	I/O, L60P_YY	I/O, L60P_YY	I/O, L60P_YY	I/O, L60P_YY
DONE	3	W20	-	-	DONE	DONE	DONE	DONE	DONE	DONE
PROGRAM	-	Y21	-	-	PROGRAM	PROGRAM	PROGRAM	PROGRAM	PROGRAM	PROGRAM
I/O (INIT), L#N_YY	3	W21	All	-	I/O (INIT), L41N_YY	I/O (INIT), L55N_YY	I/O (INIT), L59N_YY	I/O (INIT), L59N_YY	I/O (INIT), L59N_YY	I/O (INIT), L59N_YY
I/O (D7), L#P_YY	3	Y22	All	-	I/O (D7), L41P_YY	I/O (D7), L55P_YY	I/O (D7), L59P_YY	I/O (D7), L59P_YY	I/O (D7), L59P_YY	I/O (D7), L59P_YY
I/O	3	W22	-	-	-	-	-	I/O	I/O	I/O
I/O	3	V21	-	-	-	I/O	I/O	I/O	I/O	I/O

**FG676 Pinouts (XC2S400E, XC2S600E) (Continued)**

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
I/O, L164N	6	W2	XC2S600E	XC2S600E	I/O, L164N	I/O, VREF Bank 6, L164N_Y
I/O, L163P	6	W5	XC2S400E	-	I/O, L163P_Y	I/O, L163P
I/O, L163N	6	W6	XC2S400E	-	I/O, L163N_Y	I/O, L163N
I/O	6	W7	-	-	I/O	I/O
I/O, L162P_YY	6	Y1	All	-	I/O, L162P_YY	I/O, L162P_YY
I/O, L162N_YY	6	Y2	All	-	I/O, L162N_YY	I/O, L162N_YY
I/O	6	Y3	-	-	-	I/O
I/O, L161P_YY	6	Y4	All	-	I/O, L161P_YY	I/O, L161P_YY
I/O, VREF Bank 6, L161N_YY	6	Y5	All	All	I/O, VREF Bank 6, L161N_YY	I/O, VREF Bank 6, L161N_YY
I/O	6	Y6	-	-	I/O	I/O
I/O, L160P_YY	6	AA1	All	-	I/O, L160P_YY	I/O, L160P_YY
I/O, L160N_YY	6	AA2	All	-	I/O, L160N_YY	I/O, L160N_YY
I/O, L159P	6	AA3	XC2S600E	-	I/O, L159P	I/O, L159P_Y
I/O, L159N	6	AA4	XC2S600E	-	I/O, L159N	I/O, L159N_Y
I/O	6	Y7	-	-	-	I/O
I/O, L158P	6	AA5	XC2S600E	-	I/O, L158P	I/O, L158P_Y
I/O, VREF Bank 6, L158N	6	AB5	XC2S600E	All	I/O, VREF Bank 6, L158N	I/O, VREF Bank 6, L158N_Y
I/O, L157P	6	AB1	XC2S400E	-	I/O, L157P_Y	I/O, L157P
I/O, L157N	6	AB2	XC2S400E	-	I/O, L157N_Y	I/O, L157N
I/O, L156P	6	AC1	XC2S600E	-	-	I/O, L156P_Y
I/O, L156N	6	AC2	XC2S600E	-	I/O	I/O, L156N_Y
I/O, L155P_YY	6	AC3	All	-	I/O, L155P_YY	I/O, L155P_YY
I/O, L155N_YY	6	AB4	All	-	I/O, L155N_YY	I/O, L155N_YY
I/O, L154P	6	AD1	-	-	-	I/O, L154P
I/O, L154N	6	AD2	-	-	-	I/O, L154N
I/O, L153P_YY	6	AE1	All	-	I/O, L153P_YY	I/O, L153P_YY
I/O, L153N_YY	6	AF2	All	-	I/O, L153N_YY	I/O, L153N_YY
M1	-	AE3	-	-	M1	M1
M0	-	AF3	-	-	M0	M0
M2	-	AD4	-	-	M2	M2

**FG676 Pinouts (XC2S400E, XC2S600E) (Continued)**

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
I/O, L138P_YY	5	Y10	All	-	I/O, L138P_YY	I/O, L138P_YY
I/O, L137N_YY	5	AB10	All	-	I/O, L137N_YY	I/O, L137N_YY
I/O, L137P_YY	5	AC10	All	-	I/O, L137P_YY	I/O, L137P_YY
I/O	5	AD10	-	-	-	I/O
I/O, L136N	5	AE10	XC2S600E	-	I/O, L136N	I/O, L136N_Y
I/O, L136P	5	AF10	XC2S600E	-	I/O, L136P	I/O, L136P_Y
I/O	5	AD11	-	-	-	I/O
I/O, L135N_YY	5	W11	All	-	I/O, L135N_YY	I/O, L135N_YY
I/O, L135P_YY	5	Y11	All	-	I/O, L135P_YY	I/O, L135P_YY
I/O, L134N_YY	5	AA11	All	-	I/O, L134N_YY	I/O, L134N_YY
I/O, L134P_YY	5	AB11	All	-	I/O, L134P_YY	I/O, L134P_YY
I/O	5	V12	-	-	-	I/O
I/O, L133N	5	AE11	-	-	I/O, L133N	I/O, L133N
I/O, L133P	5	AF11	-	-	I/O, L133P	I/O, L133P
I/O	5	W12	-	-	-	I/O
I/O, L132N_YY	5	Y12	All	-	I/O, L132N_YY	I/O, L132N_YY
I/O, L132P_YY	5	AA12	All	-	I/O, L132P_YY	I/O, L132P_YY
I/O, VREF Bank 5, L131N_YY	5	AB12	All	All	I/O, VREF Bank 5, L131N_YY	I/O, VREF Bank 5, L131N_YY
I/O, L131P_YY	5	AC12	All	-	I/O, L131P_YY	I/O, L131P_YY
I/O	5	V13	-	-	-	I/O
I/O, L130N_YY	5	AE12	All	-	I/O, L130N_YY	I/O, L130N_YY
I/O, L130P_YY	5	AF12	All	-	I/O, L130P_YY	I/O, L130P_YY
I/O	5	W13	-	-	-	I/O
I/O, L129N	5	Y13	XC2S600E	-	I/O, L129N	I/O, L129N_Y
I/O, L129P	5	AA13	XC2S600E	-	I/O, L129P	I/O, L129P_Y
I/O, VREF Bank 5, L128N	5	AB13	XC2S600E	All	I/O, VREF Bank 5, L128N	I/O, VREF Bank 5, L128N_Y
I/O, L128P	5	AC13	XC2S600E	-	I/O, L128P	I/O, L128P_Y
I/O	5	AD13	-	-	-	I/O
I/O, L127N	5	V14	-	-	I/O	I/O, L127N
I/O, L127P	5	W14	-	-	-	I/O, L127P
I/O (DLL), L126N	5	AE13	-	-	I/O (DLL), L126N	I/O (DLL), L126N
GCK1, I	5	AF13	-	-	GCK1, I	GCK1, I

**FG676 Pinouts (XC2S400E, XC2S600E) (Continued)**

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
DONE	3	AE26	-	-	DONE	DONE
PROGRAM	-	AC24	-	-	PROGRAM	PROGRAM
I/O ( $\overline{\text{INIT}}$ ), L101N_YY	3	AD25	All	-	I/O ( $\overline{\text{INIT}}$ ), L101N_YY	I/O ( $\overline{\text{INIT}}$ ), L101N_YY
I/O (D7), L101P_YY	3	AD26	All	-	I/O (D7), L101P_YY	I/O (D7), L101P_YY
I/O, L100N	3	AC25	-	-	-	I/O, L100N
I/O, L100P	3	AC26	-	-	-	I/O, L100P
I/O, L99N	3	AB22	XC2S600E	-	-	I/O, L99N_Y
I/O, L99P	3	AB23	XC2S600E	-	I/O	I/O, L99P_Y
I/O, L98N_YY	3	AB25	All	-	I/O, L98N_YY	I/O, L98N_YY
I/O, L98P_YY	3	AB26	All	-	I/O, L98P_YY	I/O, L98P_YY
I/O, L97N	3	AA23	-	-	I/O, L97N_Y	I/O, L97N
I/O, L97P	3	AA24	-	-	I/O, L97P_Y	I/O, L97P
I/O, VREF Bank 3, L96N	3	AA25	XC2S600E	All	I/O, VREF Bank 3, L96N	I/O, VREF Bank 3, L96N_Y
I/O, L96P	3	AA26	XC2S600E	-	I/O, L96P	I/O, L96P_Y
I/O, L95N	3	AA22	XC2S600E	-	-	I/O, L95N_Y
I/O, L95P	3	Y22	XC2S600E	-	I/O	I/O, L95P_Y
I/O, L94N	3	Y23	XC2S400E	-	I/O, L94N_Y	I/O, L94N
I/O, L94P	3	Y24	XC2S400E	-	I/O, L94P_Y	I/O, L94P
I/O, L93N	3	Y25	XC2S600E	-	I/O, L93N	I/O, L93N_Y
I/O, L93P	3	Y26	XC2S600E	-	I/O, L93P	I/O, L93P_Y
I/O, VREF Bank 3, L92N_YY	3	W21	All	All	I/O, VREF Bank 3, L92N_YY	I/O, VREF Bank 3, L92N_YY
I/O, L92P_YY	3	W22	All	-	I/O, L92P_YY	I/O, L92P_YY
I/O	3	Y21	-	-	-	I/O
I/O, L91N_YY	3	W25	All	-	I/O, L91N_YY	I/O, L91N_YY
I/O, L91P_YY	3	W26	All	-	I/O, L91P_YY	I/O, L91P_YY
I/O	3	W20	-	-	I/O	I/O
I/O, L90N	3	V19	XC2S400E	-	I/O, L90N_Y	I/O, L90N
I/O, L90P	3	V20	XC2S400E	-	I/O, L90P_Y	I/O, L90P
I/O, L89N	3	V21	XC2S600E	XC2S600E	-	I/O, VREF Bank 3, L89N_Y
I/O, L89P	3	V22	XC2S600E	-	I/O	I/O, L89P_Y
I/O	3	V23	-	-	I/O	I/O
I/O, L88N_YY	3	V24	All	-	I/O, L88N_YY	I/O, L88N_YY

**FG676 Pinouts (XC2S400E, XC2S600E) (Continued)**

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
I/O, VREF Bank 1, L25P	1	D14	XC2S600E	All	I/O, VREF Bank 1, L25P	I/O, VREF Bank 1, L25P_Y
I/O, L25N	1	C14	XC2S600E	-	I/O, L25N	I/O, L25N_Y
I/O	1	J13	-	-	-	I/O
I/O, L24P	1	C13	-	-	I/O, L24P	I/O, L24P
I/O, L24N	1	D13	-	-	I/O, L24N	I/O, L24N
I/O	1	H13	-	-	-	I/O
I/O (DLL), L23P	1	B14	-	-	I/O (DLL), L23P	I/O (DLL), L23P
GCK2, I	1	A14	-	-	GCK2, I	GCK2, I
GCK3, I	0	A13	-	-	GCK3, I	GCK3, I
I/O (DLL), L23N	0	B13	-	-	I/O (DLL), L23N	I/O (DLL), L23N
I/O	0	E13	-	-	-	I/O
I/O, L22P_YY	0	F13	All	-	I/O, L22P_YY	I/O, L22P_YY
I/O, L22N_YY	0	G13	All	-	I/O, L22N_YY	I/O, L22N_YY
I/O, L21P	0	A12	XC2S600E	-	-	I/O, L21P_Y
I/O, VREF Bank 0, L21N	0	B12	XC2S600E	All	I/O, VREF Bank 0	I/O, VREF Bank 0, L21N_Y
I/O, L20P	0	D12	XC2S600E	-	I/O, L20P	I/O, L20P_Y
I/O, L20N	0	E12	XC2S600E	-	I/O, L20N	I/O, L20N_Y
I/O	0	F12	-	-	-	I/O
I/O, L19P_YY	0	G12	All	-	I/O, L19P_YY	I/O, L19P_YY
I/O, L19N_YY	0	H12	All	-	I/O, L19N_YY	I/O, L19N_YY
I/O	0	J12	-	-	-	I/O
I/O, L18P_YY	0	A11	All	-	I/O, L18P_YY	I/O, L18P_YY
I/O, VREF Bank 0, L18N_YY	0	B11	All	All	I/O, VREF Bank 0, L18N_YY	I/O, VREF Bank 0, L18N_YY
I/O, L17P_YY	0	E11	All	-	I/O, L17P_YY	I/O, L17P_YY
I/O, L17N_YY	0	F11	All	-	I/O, L17N_YY	I/O, L17N_YY
I/O	0	C11	-	-	-	I/O
I/O, L16P	0	G11	-	-	I/O, L16P	I/O, L16P
I/O, L16N	0	H11	-	-	I/O, L16N	I/O, L16N
I/O	0	C10	-	-	-	I/O
I/O, L15P_YY	0	A10	All	-	I/O, L15P_YY	I/O, L15P_YY
I/O, L15N_YY	0	B10	All	-	I/O, L15N_YY	I/O, L15N_YY
I/O, L14P_YY	0	D10	All	-	I/O, L14P_YY	I/O, L14P_YY